MICROWAVE POWER GaAs FET

Low Distortion Internally Matched Power GaAs FETs (C-Band)

Features

- · Low intermodulation distortion
 - $IM_3 = -42 \text{ dBc}$ at Po = 31.5 dBm,
 - Single carrier level
- · High power
 - P_{1dB} = 42.0 dBm at 6.4 GHz to 7.2 GHz
- High gain
 - $G_{1dB} = 7.5 dB$ at 6.4 GHz to 7.2 GHz
- · Broad band internally matched
- · Hermetically sealed package

RF Performance Specifications (Ta = 25° C)

Characteristics	Symbol	Condition	Unit	Min.	Тур.	Max
Output Power at 1dB Compression Point	P _{1dB}		dBm	41.0	42.0	_
Power Gain at 1dB Compression Point	G _{1dB}	V _{DS} = 10V	dB	6.5	7.5	_
Drain Current	I _{DS1}	f = 6.4 ~ 7.2 GHz	Α	_	4.2	5.0
Gain Flatness	ΔG		dB	_	_	±0.6
Power Added Efficiency	η _{add}		%	_	31	_
3rd Order Intermodulation Distortion	IM ₃	Note 1	dBc	-42	-45	_
Drain Current	I _{DS2}	14016 1	Α	_	4.2	5.0
Channel-Temperature Rise	ΔT_{ch}	V _{DS} xI _{DS} xR _{th} (c-c)	°C	-	_	80

Electrical Characteristics (Ta = 25° C)

Characteristic	Symbol	Condition Unit		Min.	Тур.	Max
Trans-conductance	gm	$V_{DS} = 3V$ $I_{DS} = 5.2A$	mS	_	3200	-
Pinch-off Voltage	V _{GSoff}	$V_{DS} = 3V$ $I_{DS} = 70 \text{mA}$	V	-2	-3.5	-5.0
Saturated Drain Current	I _{DSS}	$V_{DS} = 3V$ $V_{GS} = 0V$	А	_	10.0	13.0
Gate-Source Breakdown Voltage	V_{GSO}	I _{GS} = -210μA	V	-5	_	_
Thermal Resistance	R _{th (c-c)}	Channel to case	°C/W	_	1.9	2.5

Note 1: 2 tone Test Pout = 31.5dBm Single Carrier Level.

The information contained here is subject to change without notice.

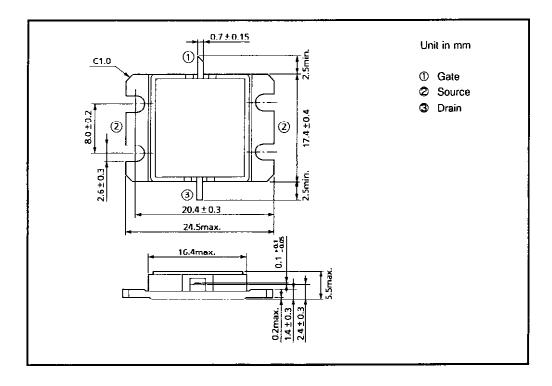
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Absolute Maximum Ratings (Ta = 25° C)

Characteristic	Symbol	Unit	Rating
Drain-Source Voltage	V _{DS}	V	15
Gate-Source Voltage	V _{GS}	V	-5
Drain Current	I _{DS}	А	13
Total Power Dissipation (T _c = 25°C)	P _T	W	60
Channel Temperature	T _{ch}	°C	175
Storage Temperature	T _{stg}	°C	-65~175

Package Outline (2-16G1B)



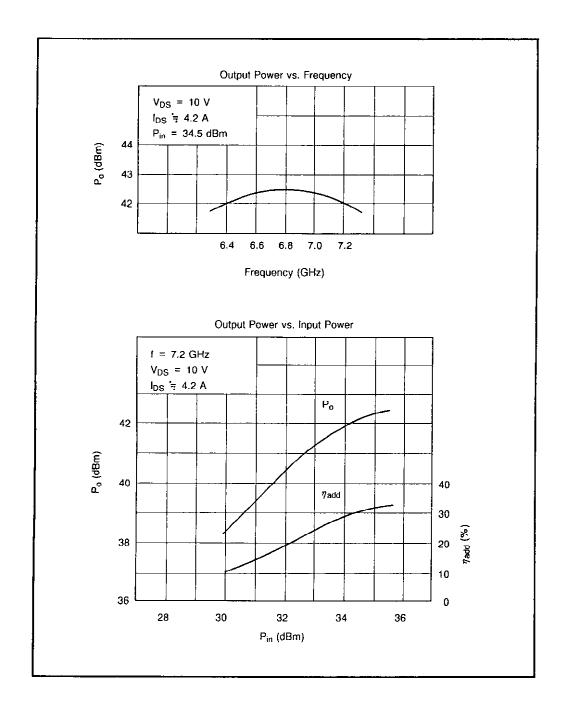
Handling Precautions for Packaged Type

Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C.

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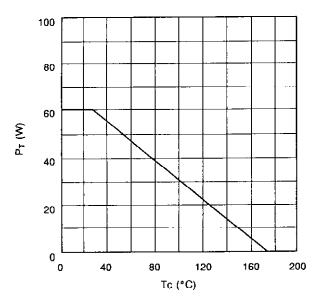
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RF Performances

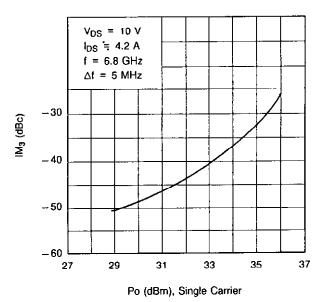


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Power Dissipation vs. Case Temperature



IM₃ vs. Output Power Characteristics

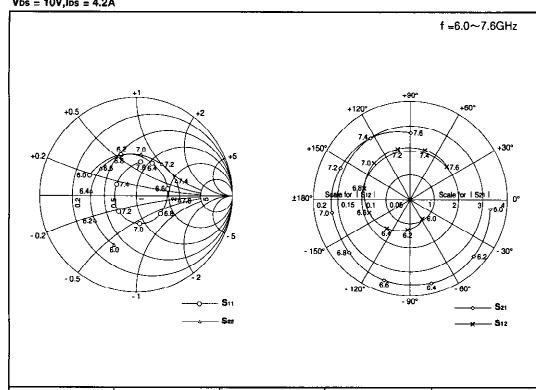


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TIM6472-14L S-Parameters (MAGN. and ANGLES)

Vos = 10V,los = 4.2A



FREQUENCY (MHz)	MAG	S11 ANG	MAG	S12 ANG	MAG	S21 ANG	MAG :	S22 ANG
6.0	0.529	157.2	0.048	-56.3	3.350	-7.0	0.558	-113.8
6.2	0.442	110.8	0.063	-94.8	3.549	-41.8	0.500	-149.5
6.4	0.372	61.6	0.078	-129.5	3.565	-75.6	0.473	175.2
6.6	0.334	12.1	0.089	-162.2	3.478	-108.1	0.462	143.6
6.8	0.315	-35.9	0.098	167.0	3.386	-139.4	0.441	114.6
7.0	0.289	-83.0	0.105	135.6	3.292	-170.8	0.416	83.1
7.2	0.243	-137.5	0.107	104.5	3.167	156.7	0.415	49.5
7.4	0.228	150.7	0.104	72.7	2.997	123.8	0.443	19.5
7.6	0.343	81.8	0.102	40.4	2.704	89.5	0.456	-5.7